

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)
 Contact Info: ti.com/support
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB
 Created on: 06/12/2022

Details for "TPS79628DRBT"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
TPS79628DRBT	NIPDAU	Level-2-260C-1 YEAR	TI MALAYSIA A/T	DRB 8	3.0x3.0x0.9	24.7

***Total Device Mass**

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
Bond Wire							
Copper and Its Alloys	Copper	7440-50-8	0.144427	99.997923	999979	0.585654	5857
Copper and Its Alloys	Iron	7439-89-6	0.000001	0.000692	7	0.000004	0
Precious Metals	Silver	7440-22-4	0.000002	0.001385	14	0.000008	0
Sub-Total			0.14443	100	1000000	0.585666	5857
Die Attach Adhesive							
Other Inorganic Materials	Silica	7631-86-9	0.011864	2.00013	20000	0.048109	481
Precious Metals	Silver	7440-22-4	0.409305	68.99996	690000	1.659739	16597
Thermoplastics	Epoxy	85954-11-6	0.172027	29.00027	290000	0.697572	6976
Sub-Total			0.593196	100	1000000	2.40542	24054
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	10.86986	99.25	992500	44.077462	440775
Other Nonferrous Metals and Alloys	Chromium	7440-47-3	0.028475	0.259998	2600	0.115467	1155
Other Nonferrous Metals and Alloys	Tin	7440-31-5	0.02738	0.25	2500	0.111026	1110
Zinc and Its Alloys	Zinc	7440-66-6	0.026285	0.240002	2400	0.106586	1066
Sub-Total			10.952	100	1000000	44.410541	444105
Lead Frame Plating							
Nickel and Its Alloys	Nickel	7440-02-0	0.187386	95.119797	951198	0.759853	7599
Precious Metals	Gold	7440-57-5	0.001537	0.780203	7802	0.006233	62
Precious Metals	Palladium	7440-05-3	0.008077	4.1	41000	0.032752	328
Sub-Total			0.197	100	1000000	0.798838	7988
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	9.805606	90.499998	905000	39.761894	397619
Other Plastics and Rubber	Carbon Black	1333-86-4	0.054175	0.500004	5000	0.219681	2197
Thermoplastics	Epoxy	85954-11-6	0.975143	8.999999	90000	3.954221	39542
Sub-Total			10.834924	100	1000000	43.935796	439358
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	1.939262	100	1000000	7.863739	78637
Sub-Total			1.939262	100	1000000	7.863739	78637
Total			24.660812			100	1000000

Important Note

The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.
 The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**.
[See Glossary of Terms for more details.](#)

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSIs or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

[For an explanation of the methods used to determine material weights, See Product Content Methodology](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

[For additional information, please contact TI customer support.](#)

[Signature: \(click here for a fuller statement with a signed certificate\)](#)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality
 For further environmental statements, please go to www.ti.com/eoinfo
 Created on: 06/12/2022

RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.